MARKET NEWS

New industrial CoolSiC™ MOSFETs 650 V G2 in TOLT and Thin-TOLL package increase system power density

Munich, Germany – 3 June 2024 – The electronics industry is witnessing a significant shift towards more compact and powerful systems, driven by technological advancements and a growing focus on decarbonization efforts. With the introduction of the Thin-TOLL 8x8 and TOLT packages, Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) is actively accelerating and supporting these trends. They enable a maximum utilization of the PCB mainboard and daughter cards, while also taking the system's thermal requirements and space restrictions into account. The company is now expanding its portfolio of CoolSiC™ MOSFET discretes 650 V with two new product families housed in the Thin-TOLL 8x8 and TOLT packages. They are based on the CoolSiC Generation 2 (G2) technology, offering significantly improved figures-of-merit, reliability, and ease-of-use. Both product families specifically target high and medium switching-mode power supplies (SMPS), including AI servers, renewable energy, EV chargers, and large home appliances.

The Thin-TOLL package has a form factor of 8x8 mm and offers the best-in-class Thermal Cycling on Board (TCoB) capability on the market. The TOLT package is a top-side cooled (TSC) enclosure with a similar form factor to TOLL. Both package types offer developers several benefits: Using them in AI and server power supply units (PSU), for example, reduces the thickness and length of the daughter cards and allows for a flat heat sink. When used in microinverters, 5G PSU, TV PSU and SMPS, the Thin-TOLL 8x8 package allows for a minimization of the PCB area occupied by the power supply devices on the mainboard, while TOLT keeps the junction temperature of the devices under control, given that these applications typically use convection cooling. In addition, TOLT devices complete Infineon's top-side cooled CoolSiC industrial portfolio, namely CoolSiC 750 V in Q-DPAK. They enable developers to reduce the PCB footprint occupied by SiC MOSFETs when the power to be delivered to the devices does not require a Q-DPAK package.

Availability

The CoolSiC MOSFETs 650 V G2 in ThinTOLL 8x8 and TOLT are now available in $R_{DS(on)}$ from 20, 40, 50 and 60 mΩ. Additionally, the TOLT variant is also available with an $R_{DS(on)}$ of 15 mΩ. The product family will be expanded by a more granular portfolio by the end of 2024. More information is available at www.infineon.com/coolsic-gen2. Infineon will showcase the CoolSiC MOSFET 650 V Generation 2 at the PCIM in Nuremberg.

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Veronika Seifried (Headquarters)	+49 89 234 61662	veronika.seifried@infineon.com	**Investor Relations:**
Agnes Toan (Americas)	+1 408 250 1814	agnes.toan@infineon.com	+49 89 234 26655
Chi Kang David Ong (Asia-Pacific)	+65 6876 3070	david.ong@infineon.com	investor.relations@infineon.com
Lin Zhu (Greater China)	+86 21 6101 9199	lin.zhu@infineon.com	
Yasuyuki Kamiseki (Japan)	+81 3 4595 7079	yasuyuki.kamiseki@infineon.com	

Infineon at the PCIM Europe 2024

PCIM Europe will take place in Nuremberg, Germany, from 11 to 13 June 2024. Infineon will present its products and solutions for decarbonization and digitalization in hall 7, booths #470 and #169. Company representatives will also be giving several presentations at the accompanying PCIM Conference and Forums, followed by discussions with the speakers. If you are interested in interviewing an expert at the show, please email media.relations@infineon.com. Industry analysts interested in a briefing can email MarketResearch.Relations@infineon.com. Information about Infineon's PCIM 2024 show highlights is available at www.infineon.com/pcim.

About Infineon

Infineon Technologies AG is a global semiconductor leader in power systems and IoT. Infineon drives decarbonization and digitalization with its products and solutions. The company has around 58,600 employees worldwide and generated revenue of about €16.3 billion in the 2023 fiscal year (ending 30 September). Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the OTCQX International over-the-counter market (ticker symbol: IFNNY).

Further information is available at www.infineon.com
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Veronika Seifried (Headquarters)	+49 89 234 61662	veronika.seifried@infineon.com	**Investor Relations:**
Agnes Toan (Americas)	+1 408 250 1814	agnes.toan@infineon.com	+49 89 234 26655
Chi Kang David Ong (Asia-Pacific)	+65 6876 3070	david.ong@infineon.com	investor.relations@infineon.com
Lin Zhu (Greater China)	+86 21 6101 9199	lin.zhu@infineon.com	
Yasuyuki Kamiseki (Japan)	+81 3 4595 7079	yasuyuki.kamiseki@infineon.com	